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List of Publications by Year
in descending order

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128 papers	2,436 citations	201674 27 h-index	289244 40 g-index
128 all docs	128 docs citations	128 times ranked	900 citing authors

#	Article	IF	Citations
1	Effects of Bi content on thermal, microstructure and mechanical properties of Sn-Bi-In-Zn solder alloy systems. Journal of Materials Science: Materials in Electronics, 2022, 33, 11-26.	2.2	4
2	Influences of Directions and Magnitudes of Static Electrical Field on Microstructure and Mechanical Properties for Alâ€“Si Eutectic Alloy. Journal of Materials Engineering and Performance, 2022, 31, 5070-5079.	2.5	5
3	Investigations of Electrical Resistivity and Thermal Conductivity Dependences on Growth Rate in the Alâ€“Cuâ€“Ti Eutectic Alloy. International Journal of Thermophysics, 2021, 42, 1.	2.1	2
4	The variations of electrical resistivity and thermal conductivity with growth rate for the Znâ€“Alâ€“Cu eutectic alloy. Journal of Materials Science: Materials in Electronics, 2021, 32, 18212-18223.	2.2	0
5	Growth of rod structure with static electrical field in the Alâ€“Ni eutectic system. Journal of Materials Science: Materials in Electronics, 2020, 31, 14055-14068.	2.2	3
6	Effects of Growth Rate on Eutectic Spacing, Microhardness, and Ultimate Tensile Strength in the Alâ€“Cuâ€“Ti Eutectic Alloy. Physics of Metals and Metallography, 2020, 121, 382-390.	1.0	2
7	Directionally Solidified Alâ€“Cuâ€“Siâ€“Fe Quaternary Eutectic Alloys. Physics of Metals and Metallography, 2020, 121, 78-83.	1.0	6
8	Electro growth of Al Cu eutectic alloy. Materials Characterization, 2020, 161, 110157.	4.4	3
9	The Variations of Electron and Phonon Contributions to the Thermal Conductivity with Temperature in the Snâ€“Biâ€“Inâ€“Zn Alternative Lead-Free Solder Alloys. Physics of Metals and Metallography, 2020, 121, 1365-1374.	1.0	1
10	BI-IN SÄ°STEMÄ°NDE ELEKTRÄ°KSEL VE ISIL Ä°LETKENLÄ°K VE ISIL Ä°LETKENLÄ°ÄžE FONON KATKISI. Isi Bilimi Ve Teknigi Dergisi/ Journal of Thermal Science and Technology, 2020, 40, 367-378.	0.6	1
11	Effect of Sn contents on thermodynamic, microstructure and mechanical properties in the Zn90â€“Bi10 and Bi88â€“Zn12 based ternary alloys. Journal of Materials Science: Materials in Electronics, 2019, 30, 3678-3691.	2.2	1
12	Thermal conductivity and electrical resistivity dependences on growth rate in the directionally solidified Alâ€“Cuâ€“Ni eutectic alloy. Journal of Alloys and Compounds, 2018, 753, 695-702.	5.5	16
13	Influence of Growth Rate on Eutectic Spacing, Microhardness, and Ultimate Tensile Strength in the Directionally Solidified Al-Cu-Ni Eutectic Alloy. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2018, 49, 3293-3305.	2.1	17
14	Thermophysical properties of NPG solid solution in the NPGâ€“SCN organic system. International Journal of Materials Research, 2018, 109, 219-224.	0.3	1
15	Microstructural, mechanical, and electrical characterization of directionally solidified Alâ€“Cuâ€“Mg eutectic alloy. Physics of Metals and Metallography, 2017, 118, 389-398.	1.0	22
16	Directional solidification of Alâ€“Cuâ€“Siâ€“Mg quaternary eutectic alloy. Journal of Alloys and Compounds, 2017, 721, 764-771.	5.5	18
17	Hardness and electrical resistivity of Alâ€“13 wt % Mg2Si pseudoeutectic alloy. Russian Journal of Non-Ferrous Metals, 2017, 58, 15-21.	0.6	4
18	Solidâ€“Liquid Interfacial Energy of Solid Succinonitrile in Equilibrium with Succinonitrileâ€“(D)Camphorâ€“Aminomethylpropanediol Eutectic Liquid. International Journal of Thermophysics, 2016, 37, 1.	2.1	0

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19	Dependence of microstructural, mechanical and electrical properties on growth rates in directional solidified Znâ€”Alâ€”Bi eutectic alloy. Transactions of Nonferrous Metals Society of China, 2016, 26, 2320-2335.	4.2	4
20	Experimental measurements of some thermophysical properties of solid CdSb intermetallic in the Snâ€“Cdâ€“Sb ternary alloy. Journal of Thermal Analysis and Calorimetry, 2016, 126, 1059-1065.	3.6	5
21	Dependence of microstructure, microhardness, tensile strength and electrical resistivity on growth rates for directionally solidified Zn-Al-Sb eutectic alloy. International Journal of Materials Research, 2016, 107, 1005-1015.	0.3	4
22	The effects of microstructure and growth rate on microhardness, tensile strength, and electrical resistivity for directionally solidified Alâ€“Niâ€“Fe alloys. Journal of Alloys and Compounds, 2016, 660, 23-31.	5.5	44
23	The measurements of electrical and thermal conductivity variations with temperature and phonon component of the thermal conductivity in Snâ€“Cdâ€“Sb, Snâ€“Inâ€“Cu, Snâ€“Agâ€“Bi and Snâ€“Biâ€“Zn alloys. International Journal of Thermal Sciences, 2016, 100, 1-9.	4.9	19
24	Thermal Conductivity of Solid Phases for Naphtol, Camphene, Salol, and Bezil. Journal of Thermophysics and Heat Transfer, 2016, 30, 730-736.	1.6	0
25	The experimental determination of thermophysical properties of intermetallic CuAl 2 phase in equilibrium with (Al + Cu + Si) liquid. Journal of Chemical Thermodynamics, 2016, 97, 228-234.	2.0	4
26	Solidâ€“liquid interfacial energy of solid succinonitrile in equilibrium with succinonitrile-1,4-diiodobenzene eutectic liquid. Journal of Thermal Analysis and Calorimetry, 2015, 119, 1867-1874.	3.6	4
27	The Experimental Determination of Interfacial Energies for Solid Zn in Equilibrium with Zn-Al-Sb Liquid. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2015, 46, 2084-2095.	2.1	1
28	Determination of thermodynamic properties of aluminum based binary and ternary alloys. Journal of Alloys and Compounds, 2015, 649, 453-460.	5.5	20
29	Thermal conductivity and interfacial energy of solid Bi in the Biâ€“Ag eutectic system. Journal of Thermal Analysis and Calorimetry, 2015, 122, 65-72.	3.6	3
30	Experimental determination of interfacial energies for solid Sn in equilibrium with Sn-Mg-Zn liquid. Metals and Materials International, 2015, 21, 286-294.	3.4	5
31	Directional solidification of Zn-Al-Cu eutectic alloy by the vertical Bridgman method. Journal of Mining and Metallurgy, Section B: Metallurgy, 2015, 51, 67-72.	0.8	7
32	Microstructural, mechanical and electrical characterization of directionally solidified Alâ€“Siâ€“Mg eutectic alloy. Journal of Alloys and Compounds, 2015, 618, 197-203.	5.5	39
33	The Measurement of Thermal Conductivity Variation with Temperature for Sn-Based Lead-Free Binary Solders. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2014, 45, 1739-1749.	2.1	6
34	Temperature dependency of thermal conductivity of solid phases for fatty acids. Journal of Thermal Analysis and Calorimetry, 2014, 118, 311-321.	3.6	21
35	The Experimental Determination of Interfacial Energies for Solid Cd in Equilibrium with Sn-Cd-Sb Liquid. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2014, 45, 1161-1170.	2.2	3
36	Solidâ€“Liquid Interfacial Energy of Solid Neopentylglycol Solution in Equilibrium with Neopentylglycolâ€“Aminomethylpropanediol Eutectic Liquid. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2013, 44, 4042-4050.	2.2	0

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37	Measurements of Thermal Conductivity Variations with Temperature for the Organic Analog of the Nonmetalâ€“Nonmetal System: Ureaâ€“4-Bromo-2-Nitroaniline. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2013, 44, 4051-4058.	2.2	0
38	The measurement of thermal conductivity variation with temperature for Sn-20wt.% In based lead-free ternary solders. Thermochimica Acta, 2013, 554, 63-70.	2.7	21
39	The influence of the growth rate on the eutectic spacings, undercoolings and microhardness of directional solidified bismuthâ€“lead eutectic alloy. Current Applied Physics, 2013, 13, 587-593.	2.4	9
40	Solidâ€“liquid interfacial energy of solid succinonitrile solution in equilibrium with succinonitrileâ€“neopentylglycol eutectic liquid. Journal of Crystal Growth, 2013, 380, 209-217.	1.5	8
41	Solidâ€“liquid interfacial energy of neopentylglycol solid solution in equilibrium with succinonitrile-neopentylglycol-aminomethylpropanediol liquid. Journal of Crystal Growth, 2013, 364, 34-39.	1.5	2
42	The measurement of interfacial energies for solid Sn solution in equilibrium with the Snâ€“Biâ€“Ag liquid. Materials Chemistry and Physics, 2013, 139, 153-160.	4.0	5
43	Influence of growth rate on microstructure, microhardness, and electrical resistivity of directionally solidified Al-7 wt% Ni hypo-eutectic alloy. Metals and Materials International, 2013, 19, 39-44.	3.4	44
44	Solidâ€“liquid interfacial energy of solid aminomethylpropanediol solution in equilibrium with aminomethylpropanediolâ€“neopentylglycolâ€“D camphor liquid. Thermochimica Acta, 2013, 554, 48-53.	2.7	2
45	The measurement of thermal conductivity variation with temperature for solid materials. Measurement: Journal of the International Measurement Confederation, 2013, 46, 161-170.	5.0	15
46	Thermal Conductivity Variation with Temperature for Lead-Free Ternary Eutectic Solders. Journal of Electronic Materials, 2013, 42, 3573-3581.	2.2	11
47	Variations of thermal conductivity with temperature and composition of Zn in the Biâ€“[x]at.% Znâ€“2at.% Al alloys. Thermochimica Acta, 2012, 547, 1-5.	2.7	9
48	Solidâ€“liquid interfacial energy of neopentylglycol solid solution in equilibrium with neopentylglycolâ€“(D) camphor eutectic liquid. Journal of Crystal Growth, 2012, 338, 181-188.	1.5	7
49	Experimental determination of interfacial energy for solid Zn solution in the Sn-Zn eutectic system. Metals and Materials International, 2012, 18, 95-104.	3.4	4
50	Effect of solidification parameters on the microstructure of directionally solidified Sn-Bi-Zn lead-free solder. Metals and Materials International, 2012, 18, 349-354.	3.4	9
51	Variations of microhardness with solidification parameters and electrical resistivity with temperature for Alâ€“Cuâ€“Ag eutectic alloy. Current Applied Physics, 2012, 12, 7-10.	2.4	25
52	Measurements of the microhardness, electrical and thermal properties of the Alâ€“Ni eutectic alloy. Materials & Design, 2012, 34, 707-712.	5.1	64
53	Thermal and electrical conductivities of silverâ€“indiumâ€“tin alloys. Journal of Physics and Chemistry of Solids, 2012, 73, 902-910.	4.0	10
54	Dependency of thermal conductivity on the temperature and composition of d-camphor in the neopentylglycolâ€“d-camphor alloys. Thermochimica Acta, 2012, 531, 12-20.	2.7	9

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55	Determination of mechanical, electrical and thermal properties of the Snâ€•Biâ€•Zn ternary alloy. Journal of Non-Crystalline Solids, 2011, 357, 2876-2881.	3.1	33
56	Microstructural characterization of unidirectional solidified eutectic Alâ€“Siâ€“Ni alloy. Materials Characterization, 2011, 62, 844-851.	4.4	35
57	Determination of solidâ€“liquid interfacial energy for a solid Sn in equilibrium with a Snâ€“Agâ€“Zn eutectic liquid. Current Applied Physics, 2011, 11, 1060-1066.	2.4	9
58	Directional solidification and physical properties measurements of the zinc-aluminum eutectic alloy. International Journal of Minerals, Metallurgy and Materials, 2011, 18, 659-664.	4.9	16
59	Dependence of Electrical Resistivity on Temperature and Sn Content in Pb-Sn Solders. Journal of Electronic Materials, 2011, 40, 195-200.	2.2	22
60	Experimental determination of thermal conductivity and interfacial energies of solid Pb solution in the Pbâ€“Sb eutectic system. Chemical Physics Letters, 2011, 503, 220-225.	2.6	2
61	Determination of thermal conductivity and interfacial energy of solid Zn solution in the Znâ€“Alâ€“Bi eutectic system. Experimental Thermal and Fluid Science, 2011, 35, 395-404.	2.7	14
62	Thermal conductivity and interfacial energies of solid Sn3Sb2 in the Snâ€“Sb peritectic system. Thermochimica Acta, 2011, 520, 25-32.	2.7	8
63	Thermal conductivity and interfacial energies of solid Sn solution in the Snâ€“Agâ€“In ternary alloy. Chemical Physics Letters, 2010, 496, 263-269.	2.6	15
64	Determination of thermo-electrical properties in Sn based alloys. Metals and Materials International, 2010, 16, 507-515.	3.4	21
65	Measurements of Microhardness and Thermal and Electrical Properties of the Binary Zn-0.7wt.%Cu Hypoperitectic Alloy. Journal of Electronic Materials, 2010, 39, 303-311.	2.2	17
66	Investigation of microhardness and thermo-electrical properties in the Snâ€“Cu hypereutectic alloy. Journal of Materials Science: Materials in Electronics, 2010, 21, 468-474.	2.2	13
67	Investigation of the effect of solidification processing parameters on the rod spacings and variation of microhardness with the rod spacing in the Snâ€“Cu hypereutectic alloy. Journal of Materials Science: Materials in Electronics, 2010, 21, 608-618.	2.2	15
68	Effect of solidification parameters on the microstructure of Sn-3.7Ag-0.9Zn solder. Materials Characterization, 2010, 61, 1260-1267.	4.4	21
69	Dependency of eutectic spacings and microhardness on the temperature gradient for directionally solidified Snâ€“Agâ€“Cu lead-free solder. Materials Chemistry and Physics, 2010, 119, 442-448.	4.0	36
70	Dependency of the thermal and electrical conductivity on the temperature and composition of Cu in the Al based Alâ€“Cu alloys. Experimental Thermal and Fluid Science, 2010, 34, 1507-1516.	2.7	62
71	Dependency of thermal and electrical conductivity on temperature and composition of Sn in Pbâ€“Sn alloys. Fluid Phase Equilibria, 2010, 295, 60-67.	2.5	21
72	Interfacial energies of solid CuAl2 in the CuAl2â€“Ag2Al pseudo binary alloy. Thin Solid Films, 2010, 518, 4322-4327.	1.8	9

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73	Thermal conductivity and interfacial energies of solid Sn in the Snâ€“Cu alloy. Chemical Physics Letters, 2010, 484, 219-224.	2.6	14
74	Thermal conductivity and interfacial energy of solid Bi solution in the Biâ€“Alâ€“Zn eutectic system. Fluid Phase Equilibria, 2010, 293, 32-41.	2.5	17
75	Experimental determination of thermal conductivity and solidâ€“liquid interfacial energy of solid Ag3Sn intermetallic in the Snâ€“Agâ€“In ternary alloy. Intermetallics, 2010, 18, 2250-2258.	3.9	17
76	Thermal and electrical conductivity of Snâ€“Agâ€“In alloys. Journal of Non-Crystalline Solids, 2010, 356, 1795-1801.	3.1	12
77	Investigation of the effect of solidification processing parameters on microhardness and determination of thermoâ€“physical properties in the Znâ€“Cu peritectic alloy. Journal of Alloys and Compounds, 2010, 491, 143-148.	5.5	15
78	Unidirectional solidification of aluminium-nickel eutectic alloy. Metallic Materials, 2010, 48, 291-300.	0.3	11
79	DETERMINATION OF ANISOTROPY OF CRYSTAL-MELT INTERFACIAL ENERGY FROM THE OBSERVED GRAIN BOUNDARY GROOVE SHAPES AT MULTIPLE ORIENTATIONS. Surface Review and Letters, 2009, 16, 579-588.	1.1	0
80	MEASUREMENTS OF SOLIDâ€“LIQUID INTERFACIAL ENERGIES IN THE ORGANIC MONOTECTIC ALLOYS. Surface Review and Letters, 2009, 16, 203-214.	1.1	3
81	Determination of interfacial energies of solid Sn solution in the Inâ€“Biâ€“Sn ternary alloy. Materials Characterization, 2009, 60, 183-192.	4.4	12
82	The dependence of lamellar spacings and microhardness on the growth rate in the directionally solidified Bi-43 wt.% Sn alloy at a constant temperature gradient. Metals and Materials International, 2009, 15, 741-751.	3.4	12
83	Directional solidification of Alâ€“Cuâ€“Ag alloy. Applied Physics A: Materials Science and Processing, 2009, 95, 923-932.	2.3	59
84	Thermal conductivities of solid and liquid phases for neopentylglycol, aminomethylpropanediol and their binary alloy. Journal of Physics and Chemistry of Solids, 2009, 70, 72-78.	4.0	31
85	Determination of interfacial energies in the aminomethylpropanediol-neopentylglycol organic alloy. Applied Surface Science, 2009, 255, 3594-3599.	6.1	11
86	Interfacial energies of carbon tetrabromide. Current Applied Physics, 2009, 9, 359-366.	2.4	3
87	Unidirectional solidification of Zn-rich Zn-Cu hypoperitectic alloy. Journal of Materials Research, 2009, 24, 3422-3431.	2.6	14
88	Investigation of directional solidified Alâ€“Ti alloy. Journal of Non-Crystalline Solids, 2009, 355, 1231-1239.	3.1	5
89	The effect of growth rate on microstructure and microindentation hardness in the Inâ€“Biâ€“Sn ternary alloy at low melting point. Journal of Alloys and Compounds, 2009, 470, 150-156.	5.5	43
90	Novel experimental technique to observe equilibrated grain boundary groove shapes in opaque alloys. Journal of Alloys and Compounds, 2009, 476, 213-219.	5.5	21

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91	Dependency of microindentation hardness on solidification processing parameters and cellular spacing in the directionally solidified Al based alloys. Journal of Alloys and Compounds, 2009, 478, 281-286.	5.5	36
92	The microstructure parameters and microhardness of directionally solidified Snâ€“Agâ€“Cu eutectic alloy. Journal of Alloys and Compounds, 2009, 485, 264-269.	5.5	43
93	Experimental investigation of the effect of solidification processing parameters on the rod spacings in the Snâ€“1.2wt.% Cu alloy. Journal of Alloys and Compounds, 2009, 486, 199-206.	5.5	44
94	Experimental determination of solidâ€“solid and solidâ€“liquid interfacial energies of solid É› (CuZn5) in the Znâ€“Cu alloy. Journal of Alloys and Compounds, 2009, 487, 103-108.	5.5	10
95	Determination of interfacial energies in the Alâ€“Ag and Snâ€“Ag alloys by using Bridgman type solidification apparatus. Journal of Alloys and Compounds, 2009, 488, 138-143.	5.5	22
96	Solidâ€“liquid interfacial energy of neopentylglycol. Journal of Colloid and Interface Science, 2008, 320, 555-562.	9.4	23
97	Effects of growth rate and temperature gradient on the microstructure parameters in the directionally solidified succinonitrileâ€“7.5wt.% carbon tetrabromide alloy. Journal of Materials Processing Technology, 2008, 202, 145-155.	6.3	5
98	Variation of microindentation hardness with solidification and microstructure parameters in the Al based alloys. Applied Surface Science, 2008, 255, 3071-3078.	6.1	62
99	Interfacial Energy of Solid Bismuth in Equilibrium with Bi-In Eutectic Liquid at 109.5 â„ƒ Equilibrating Temperature. Metals and Materials International, 2008, 14, 177-187.	3.4	11
100	Dependency of Microstructural Parameters and Microindentation Hardness on the Temperature Gradient in the In-Bi-Sn Ternary Alloy with a Low Melting Point. Metals and Materials International, 2008, 14, 575-582.	3.4	18
101	Investigation of liquid composition effect on Gibbsâ€“Thomson coefficient and solidâ€“liquid interfacial energy in SCN based binary alloys. Materials Characterization, 2008, 59, 998-1006.	4.4	23
102	Interfacial energy of solid In2Bi intermetallic phase in equilibrium with Inâ€“Bi eutectic liquid at 72ÂÂ°C equilibrating temperature. Materials Characterization, 2008, 59, 1101-1110.	4.4	20
103	Solidâ€“liquid interfacial energy of aminomethylpropanediol. Journal Physics D: Applied Physics, 2008, 41, 065309.	2.8	27
104	Determination of solidâ€“liquid interfacial energies in the Inâ€“Biâ€“Sn ternary alloy. Journal Physics D: Applied Physics, 2008, 41, 175302.	2.8	9
105	Solidâ€“liquid interfacial energy of the solid Mg2Zn11phase in equilibrium with Znâ€“Mg eutectic liquid. Journal of Physics Condensed Matter, 2007, 19, 176003.	1.8	30
106	Solidâ€“liquid interfacial energy of dichlorobenzene. Journal of Physics Condensed Matter, 2007, 19, 116202.	1.8	25
107	Measurement of solidâ€“liquid interfacial energy in the Inâ€“Bi eutectic alloy at low melting temperature. Journal of Physics Condensed Matter, 2007, 19, 506102.	1.8	16
108	Effect of solidification processing parameters on the cellular spacings in the Alâ€“0.1wt% Ti and Alâ€“0.5wt% Ti alloys. Journal of Alloys and Compounds, 2007, 439, 114-127.	5.5	38

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109	Thermal conductivities of solid and liquid phases in Pbâ€“Cd and Snâ€“Zn binary eutectic alloys. Thermochimica Acta, 2007, 454, 128-134.	2.7	33
110	Interfacial energies of p-dichlorobenzeneâ€“succinonitrile alloy. Thermochimica Acta, 2007, 463, 44-52.	2.7	11
111	Measurement of Solid-Liquid Interfacial Energy for Solid Zn in Equilibrium with the ZnMg Eutectic Liquid. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2007, 38, 1539-1545.	2.2	8
112	Solidâ€“liquid interfacial energy for solid succinonitrile in equilibrium with succinonitrile dichlorobenzene eutectic liquid. Thermochimica Acta, 2006, 445, 86-91.	2.7	25
113	Experimental determination of solidâ€“liquid interfacial energy for succinonitrile solid solution in equilibrium with the succinonitrileâ€“(D) camphor eutectic liquid. Journal of Materials Science, 2006, 41, 7939-7943.	3.7	17
114	Measurement of solidâ€“liquid interfacial energy for solid d-camphor solution in equilibrium with succinonitrile d-camphor eutectic liquid. Scripta Materialia, 2006, 55, 235-238.	5.2	33
115	Measurement of solidâ€“liquid interfacial energy in the pyrene succinonitrile monotectic system. Journal of Physics Condensed Matter, 2006, 18, 8403-8412.	1.8	22
116	Solid-liquid interfacial energy of pyrene. Journal of Applied Physics, 2006, 100, 123505.	2.5	28
117	Dependency of the dendritic arm spacings and tip radius on the growth rate and composition in the directionally solidified succinonitrileâ€“carbon tetrabromide alloys. Journal of Crystal Growth, 2005, 276, 583-593.	1.5	26
118	Measurement of solidâ€“liquid interfacial energy in succinonitrileâˆ’pyrene eutectic system. Materials Letters, 2005, 59, 2953-2958.	2.6	27
119	Solidâ€“liquid interfacial energy of the eutectoid Î² phase in the Alâ€“Zn eutectic system. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2004, 369, 294-301.	5.6	76
120	Experimental determination of solidâ€“liquid interfacial energy for solid Cd in Biâ€“Cd liquid solutions. Journal of Alloys and Compounds, 2004, 385, 207-213.	5.5	35
121	Solidâ€“liquid interface energies in the succinonitrile and succinonitrileâ€“carbon tetrabromide eutectic system. Journal of Crystal Growth, 2003, 247, 613-622.	1.5	60
122	Effect of growth rate and composition on the primary spacing, the dendrite tip radius and mushy zone depth in the directionally solidified succinonitrileâ€“Salol alloys. Journal of Crystal Growth, 2003, 255, 190-203.	1.5	30
123	Solidâ€“liquid interfacial energy of camphene. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 1999, 270, 343-348.	5.6	62
124	The use of measured values of surface energies to test heterogeneous nucleation theory. Journal of Crystal Growth, 1998, 191, 558-562.	1.5	7
125	Solidâ€“liquid surface energy of pivalic acid. Journal of Crystal Growth, 1998, 194, 119-124.	1.5	77
126	Solid-liquid surface energies in the Alî—¸CuAl2, Alî—¸NiAl3 and Alî—¸Ti systems. Acta Materialia, 1996, 44, 1085-1096.	7.9	158

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127	The effect of different atomic volumes in the three phases during lamellar eutectic growth. A comparison of experiment and theory in the Alî—Al2Cu system. Acta Metallurgica Et Materialia, 1995, 43, 2143-2147.	1.8	18
128	Solidification of A356 Alloy Under Different Directions and Magnitudes of Static Electrical Field. International Journal of Metalcasting, 0, , 1.	1.9	3